

Upcoming: April 5–9, MRS Spring Meeting, MRS.

To list an event in the Calendar, contact J. Meiksin, Materials Research Society, 506 Keystone Drive, Warrendale, PA 15086-7573; 724-779-3004 ext. 522; fax 724-779-8313.

MRS, A-MRS, C-MRS, E-MRS, MRS-A, MRS-I, MRS-J, MRS-K, MRS-R, MRS-T, M-MRS, or IUMRS at the end of an entry indicates sponsorship or co-sponsorship of an event by the International Union of Materials Research Societies or one of its adhering bodies. "Endorsed" identifies events endorsed by MRS.

▼ identifies a new or revised entry this month.

See the January 1999 MRS BULLETIN for March 1999 Calendar entries.

APRIL 1999

5–9 MRS Spring Meeting, San Francisco, CA. Materials Research Society, 506 Keystone Drive, Warrendale, PA 15086-7573; 724-779-3003; fax 724-779-8313; <http://www.mrs.org/>. **MRS.**

6–9 ▼ Intl. Conf. on High Density Packaging and MCMs, *Denver, CO.* HDP/MCM: Denver '99, Intl. Microelectronics and Packaging Society, 1850 Centennial Park Dr., Ste. 105, Reston, VA 20191-1517; 703-758-1060; fax 703-758-1066; e-mail imaps@imaps.org; www.imaps.org.

9–11 ▼ National SBIR Conf., *Washington, DC.* U.S. Dept. of Defense, National Science Foundation, and Small Business Administration; 561-791-0720; fax 561-791-0098; e-mail teddy@seeport.com; www.seeport.com.

10 ▼ Intl. Symposium on Solid Electrolytes, *Bethlehem, PA.* Department of Materials Science and Engineering, Lehigh University, Bethlehem, PA 18015, c/o Himanshu Jain, e-mail hj00@lehigh.edu or G.S. Cargill III, e-mail gsc3@lehigh.edu.

11–15 12th Intl. Conf. on 3-D Image Processing in Microscopy and 11th Intl. Conf. on Confocal Microscopy, *Heidelberg, Germany.* Royal Microscopical Society, 37/38 St. Clements, Oxford OX4 1AJ, UK; 44-1865-248768; fax 44-1865-791237; e-mail meetings@rms.org.uk; <http://www.rms.org.uk>.

11–15 AWS Intl. Welding and Fabricating Conf., *St. Louis, MO.* Conf. Dept., American Welding Society, 550 N.W. LeJeune Rd., Miami, FL 33126; 305-443-9353; fax 305-443-7559; e-mail info@aws.org; <http://www.aws.org>.

12–14 MSRI Conf. on Self-Assembling Geometric Structures in Material Science: The Geometry of Interfaces in Mesoscopic Materials, *Berkeley, CA.* Mathematical Sciences Research Inst., 1000 Centennial Dr., Berkeley, CA 94720; 510-642-0143; fax 510-642-8609; <http://www.msri.org>.

12–15 ▼ 40th AIAA/ASME/ASCE/AHS/ASC Structures, Structural Dynamics, and Materials Conf., *St. Louis, MO.* American Inst. of Aeronautics and Astronautics, 1801 Alexander Bell Dr., Ste. 500, Reston, VA 20191-4344; 703-264-7500; <http://www.aiaa.org>.

12–16 26th Intl. Conf. on Metallurgical Coatings and Thin Films, *San Diego, CA.* M.S. Gray, ICMCTF, Ste. 136, 14011-F St. Germain Dr., Centerville, VA 20121; fax 703-968-8877; e-mail icmctf@mindspring.com.

12–16 ▼ OSA Confs. on Optics in Computing; Spatial Light Modulators; Quantum Optoelectronics; and Ultrafast Electronics and Optoelectronics; *Snowmass, CO.* Optical Society of America, Conf. Services Dept., 2010 Massachusetts Ave., N.W., Washington, DC 20036-1023; 202-416-1980; fax 202-416-6100; e-mail confserv@osa.org; <http://www.osa.org/mtg-conf>.

13–16 13th Optical Fiber Sensors Conf., *Kyongju, Korea.* OFS-13 Secretariat, KAIST, Dept. of Physics, 373-1, Kusong-dong, Yusong-gu, Taejon 305-701, Korea; 82-42-869-8351/8171; fax 82-42-869-8350/5527; e-mail ejsohn@cais.kaist.ac.kr.

14 Microscopy of Biomaterials III Meeting, *London, UK.* Royal Microscopical Society, 37/38 St. Clements, Oxford OX4 1AJ, UK; 44-1865-248768; fax 44-1865-791237; e-mail meetings@rms.org.uk; <http://www.rms.org.uk>.

14–16 ▼ 2nd Intl. Conf. on Hard Ferrites, *San Francisco, CA.* C. Jones, Gorham/Intertech Consulting, P.O. Box 250, Gorham, ME 04038; 207-892-5445; fax 207-892-2210; e-mail gorham@goradv.com.

14–16 ▼ 24th Annual AAAS Colloquium on Science and Technology Policy, *Washington, DC.* D. Amber, American Assoc. for the Advancement of Science, 1200 New York Ave. N.W., Washington, DC 20005; 202-326-6434; fax 202-789-0455; e-mail damber@aaas.org.

17–22 SVC 42nd Technical Conf., *Chicago, IL.* Society of Vacuum Coaters, 71 Pinon Hill Place N.E., Albuquerque, NM 87122-1914; 505-856-7188; fax 505-856-6716; e-mail svinfo@svc.org; <http://www.svc.org>.

19–21 MSM 99—International Conference on Modeling and Simulation of Microsystems, *Puerto Rico, USA.* USA website: <http://www.iamcm.org/MSM99>; Europe website: <http://dmtwww.epfl.ch/MSM99>.

19–23 10th Intl. Conf. on Modern Trends in Activation Analysis, *Bethesda, MD.* R.M. Lindstrom, Natl. Inst. of Standards and Technology, B125 Bldg. 235, Gaithersburg, MD 20899; fax 301-208-9279; e-mail mtaa10@nist.gov; <http://www.cstl.nist.gov/nist839/839.05/nuclear.htm>.

19–24 Hannover Fair '99—World Center for Industrial Technology, *Hannover, Germany.* A. Anderson, Hannover Fairs USA, Inc., 103 Carnegie Ctr., Princeton, NJ 08540; 609-987-1202; fax 609-987-0092; e-mail hannoverfair@hfusa.com; <http://www.hfusa.com>.

22 ▼ Ion Implant User Group Spring Meeting, *Boston, MA.* J. Albers, NIST, Bldg. 225, Rm. B-310, Gaithersburg, MD 20899; 301-975-2075; fax 301-948-4081; e-mail john.albers@nist.gov; <http://ray.eel.nist.gov/iug>.

25–28 101st ACerS Annual Meeting, *Indianapolis, IN.* Customer Service Dept., American Ceramic Society, P.O. Box 6136, Westerville, OH 43086-6136; 614-794-5890; fax 614-899-6109; e-mail customersvc@acers.org; <http://www.acers.org>.

25–28 NAFEMS World Congress on Effective Engineering Analysis, *Newport, RI.* NAFEMS Ltd., Whitworth Bldg., Scottish Enterprise Technology Park, East Kilbride G75 0QD, UK; 44-13-55-27-2639; fax 44-13-55-27-2749; e-mail tkenny@nafems.org; <http://www.nafems.org/nwe99>.

26–27 ▼ Materials Discovery, Synthesis, and Optimization for the Commercialization of Both Small Molecule and Polymer Light Emitting Devices, *San Diego, CA.* The Knowledge Foundation, 101 Merrimac, Boston, MA 02114; 617-367-7979; fax 617-367-7912; e-mail custserv@knowledgefoundation.com; www.knowledgefoundation.com.

26–28 ▼ Adhesive and Coating Adhesion: Theory, Applications, and Durability, *Chicago, IL.* Inst. of Materials Science—SUNY, P.O. Box 369, New Paltz, NY 12561; 914-255-0757; fax 914-255-0978; e-mail spinquiry@ims-np.org; <http://www.ims-np.org/springadh>.

26–28 ▼ Introduction to Emulsion Polymers/Polymer Colloids, *Chicago, IL.* Inst. of Materials Science—SUNY, P.O. Box 369, New Paltz, NY 12561; 914-255-0757; fax 914-255-0978; e-mail spinquiry@ims-np.org; <http://www.ims-np.org/springcol>.

26–29 ▼ Pigment Dispersions: Science and Technology, *Chicago, IL.* Inst. of Materials Science—SUNY, P.O. Box 369, New Paltz, NY 12561; 914-255-0757; fax 914-255-0978; e-mail spinquiry@ims-np.org; <http://www.ims-np.org/springpig>.

28–1 25th Annual Meeting of the Society for Biomaterials, *Providence, RI.* Society for Biomaterials; 612-927-8108; <http://www.biomaterials.org>.

29–30 ▼ Commercialization of Fuel Cells for Portable Applications, *Washington, DC.* The Knowledge Foundation, 101 Merrimac, Boston, MA 02114; 617-367-7979; fax 617-367-7912; e-mail custserv@knowledgefoundation.com; www.knowledgefoundation.com.

29–1 Intl. Conf. on Fundamental Physics in Space, *Washington, DC.* P. McLane, Jet Propulsion Lab., Mail Station T-1200, 4800 Oak Grove Dr., Pasadena, CA 91109; 818-354-5556; fax 818-393-4992; e-mail conf.admin@jpl.nasa.gov; <http://www.jpl.nasa.gov/physics>.

MAY 1999

2–7 ECS—Electrochemical Society Spring Meeting, *Seattle, WA.* The Electrochemical Society Inc., 10 South Main Street, Pennington, NJ 08534-2896, USA; e-mail ecs@electrochem.org; <http://www.electrochem.org/meetings/195/meet.html>.

3–7 6th European Workshop on Modern Developments and Applications in Microbeam Analysis, *Konstanz, Germany.* EMAS Secretariat, Univ. of Antwerp, Dept. of Chemistry, Universiteitsplein 1, B-2610 Antwerp-Wilrijk, Belgium; fax 32-3-820-3276; e-mail vandack@uia.ua.ac.be.

9–11 ▼ 4th Intl. Symposium on Plasma Process-Induced Damage, *Monterey, CA.* NCCAVS Business Office; 408-737-0767; fax 408-737-2403; e-mail nccavs@technicalmarketing.com; www.vacuum.org/nccavs/p2id.

16–20 9th Biennial Workshop on Organometallic Vapor Phase Epitaxy, *Ponte Vedra Beach, FL.* Customer Service Dept., TMS, 420 Commonwealth Dr., Warrendale, PA 15086; 724-776-9000; fax 724-776-3770; e-mail csc@tms.org; <http://www.tms.org>.

19–21 ▼ Intl. Symposium on Microelectronic Manufacturing Technologies, *Edinburgh, Scotland, UK.* Europto Series, Microelectronic Manufacturing Technologies, Blvd. St. Michel 15, B-1040 Brussels, Belgium; 32-2-743-1573; fax 32-2-743-1550; e-mail debby@associationhq.com; <http://www.europto.org>.

22–27 American Crystallographic Assoc. Annual Meeting in conjunction with the American Assoc. for Crystal Growth, *Buffalo, NY.* American Crystallographic Assoc., P.O. Box 96, Ellicott Station, Buffalo, NY 14205-0096; 716-856-9600; fax 716-852-4846; e-mail aca@hwi.buffalo.edu; <http://www.hwi.buffalo.edu/aca/>.

23–27 9th Biennial Workshop on Organometallic Vapor Phase Epitaxy, *Ponte Vedra Beach, FL.* TMS, Customer Service Dept., 420 Commonwealth Dr., Warrendale, PA 15086-7514; 724-776-9000; fax 724-776-3770; e-mail csc@tms.org; <http://www.tms.org/meetings/meetings.html>.

23–27 ▼ 44th Intl. SAMPE Symposium, *Long Beach, CA.* Society for the Advancement of Material and Process Engineering, 1161 Parkview Dr., Covina, CA 91724-3748; 626-331-0616; fax 626-332-8929; e-mail sampeibo@aol.com; www.et.byu.edu/~sampe.

23-28 Conf. on Lasers and Electro-Optics, and Quantum Electronics and Laser Science Conf., *Baltimore, MD*. Optical Society of America, Conf. Services Dept., 2010 Massachusetts Ave., N.W., Washington, DC 20036-1023; 202-416-1980; fax 202-416-6100; e-mail confserv@osa.org; <http://www.osa.org/mtg-conf>.

24-26 2nd Intl. Symposium on Polymer Surface Modification: Relevance to Adhesion, *Newark, NJ*. R.H. Lacombe, Conf. Chair, C4 Technologies, Inc., 3 Hammer Dr., Hopewell Junction, NY 12533; 914-227-7026; fax 212-656-1016; e-mail rhacombe@compuserve.com; <http://ourworld.compuserve.com/homepages/rhacombe/conf.htm>.

27-28 2nd Intl. Symposium on Plasma Polymerization/Deposition: Fundamental and Applied Aspects, *Newark, NJ*. R.H. Lacombe, Conf. Chair, C4 Technologies, Inc., 3 Hammer Dr., Hopewell Junction, NY 12533; 914-227-7026; fax 212-656-1016; e-mail rhacombe@compuserve.com; <http://ourworld.compuserve.com/homepages/rhacombe/conf.htm>.

30-3 10th Intl. Symposium on Intercalation Compounds, *Okazaki, Japan*. T. Enoki, ISIC 10, Dept. of Chemistry, Tokyo Inst. of Technology, Ookayama, Meguro-ku, Tokyo 152-8551, Japan; fax 81-3-5734-2242; e-mail isic@chem.titech.ac.jp; <http://www.chem.titech.ac.jp/~isic/>.

JUNE 1999

1-4 43rd Intl. Conf. on Electron, Ion, and Photon Beam Technology and Nanofabrication, *Marco Island, FL*. Mark Gesley Etec Systems, 26460 Corporate Ave., Hayward, CA 94545; 510-887-3312; fax 510-7876-9438; e-mail gesley@etec.com; <http://www.eecs.umich.edu/~pang>.

1-4 E-MRS Spring Meeting, *Strasbourg, France*. E-MRS, B.P. 20, 67037 Strasbourg Cedex 2, France; 33-3-8810-6343; e-mail emrs@phase.c-strasbourg.fr; <http://www-emrs.c-strasbourg.fr>. **E-MRS.**

6-10 12th Intl. Colloquium on Plasma Processes, *Antibes - Juan-les-Pins, France*. SFV, 19 rue du Renard, F-75004, Paris, France; e-mail stfv@club-internet.fr.

7-9 2nd ISOPE European Offshore Mechanics Symposium: Intl. Pipeline Symposium, *Moscow, Russia*. Intl. Society of Offshore and Polar Engineers, P.O. Box 1107, Golden, CO 80402-1107; 303-420-8114; fax 303-420-3760.

7-10 2nd Worldwide Aerospace Conf., *Long Beach, CA*. D. Baker, Conf. Coordinator, The MacNeal-Schwendler Corp., 815 Colorado Blvd., Los Angeles, CA 90041-1777; 323-259-3862; fax 323-259-4969; www.macsch.com/aerospace.

7-10 10th Intl. Conf. on Solid-State Sensors and Actuators, *Sendai, Japan*. Transducers '99, J. Echizen, 103, Honcho 2-41-16, Nakano-ku, Tokyo 164-0012, Japan; 81-3-3299-1371; fax 81-3-3299-1361; e-mail tr99@twics.com; <http://www.com.cas.uec.ac.jp/trans99.html>.

8-12 7th Intl. Conf. on Fatigue, *Beijing, China*. X.Y. Huang, Beijing Inst. of Aeronautical Materials, P.O. Box 81-23, Beijing 100095, P.R. China; 86-10-62458125; fax 86-10-62456925; e-mail mechbiam@public3.bta.net.cn. **C-MRS.**

9 Composites: From Nano to Macro, *Storrs, CT*. Y.H. Chudy, Institute of Materials Science, University of Connecticut, Storrs, CT 06269-3136; 860-486-3582; fax 860-486-4745; e-mail yhchudy@mail.ims.uconn.edu.

9-11 Intl. Conf. on Hot Isostatic Pressing, *Beijing, China*. HIP'99, H. Jingyong, Chinese Materials Research Society, No. 7 Baishiqiao Rd., Beijing 100081, China; phone/fax 86-10-68428640; e-mail cmrsec@public.bta.net.cn. **C-MRS.**

9-11 OSA Topical Meeting on Optical Amplifiers and Their Applications, *Nara City, Japan*. Optical Society of America, Conf. Services Dept., 2010 Massachusetts Ave., N.W., Washington, DC 20036-1023; 202-416-1980; fax 202-416-6100; e-mail confserv@osa.org; <http://www.osa.org/mtg-conf>.

13-18 5th IUMRS-ICAM'99, *Beijing, China*. Secretariat, IUMRS-ICAM-1999, C-MRS Office, 7 Baishiqiao Road, Beijing, 100081, China; 86-10-68428640; fax 86-10-68428640; http://www.chimeb.edu.cn/meeting/e_mrs99.htm. **IUMRS, MRS-I.**

14-16 Intl. Conf. on Metal Foams and Porous Metal Structures, *Bremen, Germany*. A. Böker, Conf. Secretariat, Fraunhofer Inst., Lesumer Heerstr. 36, D-28717 Bremen, Germany; 49-421-6383-211; fax 49-421-6383-190; e-mail bk@ifam.fhg.de; <http://www.ifam.fhg.de/fhg/ifam/metfoam99.html>.

14-17 Surface Analysis Conf., *Waukesha, WI*. T. Barr, Dept. of Materials, Univ. of Wisconsin, Milwaukee, WI 53201; 414-229-4085; fax 414-229-6958; e-mail terybarr@csd.uwm.edu; <http://www.vacuum.org/assd/surf99.html>.

16-18 5th Intl. Symposium on Sputtering and Plasma Processes, *Kanazawa, Japan*. S. Daikuhara, ISSP'99 Committee Chair, SHIN-CRON Co., Ltd.; 81-3-3762-7812; fax 81-3-3762-8075; e-mail s051daikuhara@shincron.co.jp.

20-23 MCM Applications Conf., *Newport, RI*. Intl. Microelectronics and Packaging Society, 1850 Centennial Park Dr., Ste. 105, Reston, VA 20191-1517; 703-758-1060; fax 703-758-1066; e-mail imaps@imaps.org; www.imaps.org.

20-24 Intl. Conf. on Powder Metallurgy and Particulate Materials, *Vancouver, Canada*. Metal Powder Industries Federation, 105 College Rd. East, Princeton, NJ 08540-6692; 609-452-7700; fax 609-987-8523; www.mpif.org.

21-24 4th Intl. Airborne Remote Sensing Conf., *Ottawa, Ontario, Canada*. ERIM Airborne Conf., Box 134008, Ann Arbor, MI 48113-4008; 734-994-1200, ext. 3234; fax 734-994-5123; e-mail wallman@erim-int.com; <http://www.erim-int.com/conf/conf.html>.

21-24 OSA Topical Meeting on Optical Remote Sensing of the Atmosphere, with the OSA Topical Meeting on Fourier Transform Spectroscopy: New Methods and Applications, *Santa Barbara, CA*. Optical Society of America, Conf. Services Dept., 2010 Massachusetts Ave., N.W., Washington, DC 20036-1023; 202-416-1980; fax 202-416-6100; e-mail confserv@osa.org; <http://www.osa.org/mtg-conf>.

21-25 5th Intl. Conf. on Electrical Transport and Optical Properties of Inhomogeneous Media, *Hong Kong, Conf.* Secretariat, ETOPIIMS, c/o H. Lai, Dept. of Physics, The Hong Kong Univ. of Science and Technology, Clear Water Bay, Kowloon, Hong Kong; 852-2358-7500; fax 852-2358-1652; e-mail etopim@uxmail.ust.hk; <http://physics.ust.hk/etopim5>.

23-25 21st Annual Intl. Conf. on the Degradation and Stabilization of Polymers, *Interlaken, Switzerland*. A.V. Patsis, Inst. of Materials Science, State Univ. of New York at New Paltz, New Paltz, NY 12561; 914-255-0757; fax 914-255-0978; e-mail icinqury@ims-np.org; <http://www.ims-np.org/interDeg>.

27-30 ISTE/MRS Intl. Workshop on Superconductivity, *Kauai, HI*. T. Kobayashi, Secretariat, Intl. Superconductivity Technology Center, Eishin Kaihatsu Bldg. 6F, 34-3, Shimbashi 5-chome, Minato-ku, Tokyo 105-0004, Japan; 81-3-3431-4002; fax 81-3-3431-4044; e-mail t-kobayashi@istec.or.jp. **MRS.**

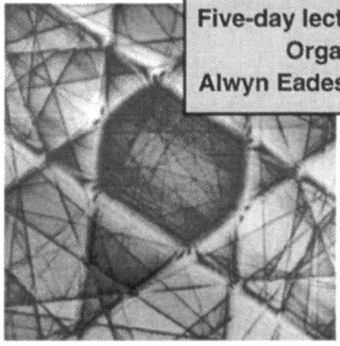
27-30 OSA Topical Meeting on Applications of High Field and Short Wavelength Sources VIII, *Potsdam, Germany*. Optical Society of America, Conf. Services Dept., 2010 Massachusetts Ave., N.W., Washington, DC 20036-1023; 202-416-1980; fax 202-416-6100; e-mail confserv@osa.org; <http://www.osa.org/mtg-conf>.

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For more information CONTACT:

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Phone: 610/758-5133
e-mail: Sharon.Coe@Lehigh.edu
<http://www.lehigh.edu/~inmatsci/Microcourses.html>

Circle No. 14 on Reader Service Card.

27-2 Intl. Conf. on Mechanical Properties of Films, Coatings, and Interfacial Materials, *Il Ciocco (Barga), Italy*. Engineering Foundation Conf., 3 Park Ave., 27th Floor, New York, NY 10016; 212-591-7836; fax 212-591-7441; e-mail engfnd@aol.com; <http://www.engfnd.org>.

27-2 Shock Compression of Condensed Matter, *Snowbird, UT*. Meetings Dept., American Physical Society, One Physics Ellipse, College Park, MD 20740-3844; 301-209-3286; <http://www.aps.org>.

30-2 41st Electronic Materials Conf., *Santa Barbara, CA*. Customer Service Dept., TMS, 420 Commonwealth Dr., Warrendale, PA 15086; 724-776-9000; fax 724-776-3770; e-mail csc@tms.org; <http://www.tms.org>.

JULY 1999

3-7 4th Liquid Matter Conf., *Granada, Spain*. R. Hidalgo Alvarez, Dept. Física Aplicada, Facultad de Ciencias, Univ. de Granada, Campus de Fuentenueva, E-18071 Granada, Spain; 34-958-243-213; fax 34-958-243-214; e-mail liquid99@ugr.es; <http://www.ugr.es/~liquid99>.

5-9 3rd Intl. Conf. on Nitride Semiconductors, *Montpellier, France*. P. Lefebvre, Secretary ICNS3, Univ. de Montpellier II, Groupe d'Etude des Semiconducteurs, Case Courrier 074, 34095 Montpellier Cedex 5, France; 33-0-4-67-14-37-56; fax 33-0-4-67-14-37-60; e-mail lefebvre@ges.univ-montp2.fr.

5-9 25th Annual Intl. Conf. on Organic Coatings: Waterborne, High Solids, and Powdered Coatings, *Athens, Greece*. A.V. Patsis, Inst. of Materials Science, State Univ. of New York at New Paltz, New Paltz, NY 12561; 914-255-0757; fax 914-255-0978; e-mail icinquiry@ims-np.org; <http://www.ims-np.org/interOrg>.

6-9 Intl. Workshop on Adaptive Optics for Industry and Medicine, *Durham, England*. G.D. Love, Univ. of Durham, Dept. of Physics, Science Laboratories, South Rd., Durham DH1 3LE, UK; 44-191-374-7496; 44-191-374-3709; e-mail g.d.love@durham.ac.uk.

7-9 59th Annual Physical Electronics Conf., *Berkeley, CA*. K. Copp, PEC Conf. Secretariat, L-356, Lawrence Livermore Natl. Lab., 7000 East Ave., P.O. Box 808, Livermore, CA 94550; 925-424-2597; fax 925-424-4737; e-mail copp@llnl.gov; <http://www.physicalelectronics.org>.

11-16 Ultrafast Optics Meeting, *Ascona, Switzerland*. U. Keller, Swiss Federal Inst. of Technology Zurich, Inst. of Quantum Electronics, ETH Honggerberg HPT, CH-8093 Zurich, Switzerland; 41-1-633-2146; fax 41-2-633-1059; e-mail keller@iqe.phys.ethz.ch.

12 FEG Electron Microscopy Meeting, *Oxford, UK*. Royal Microscopical Society, 37/38 St. Clements, Oxford OX4 1AJ, UK; 44-1865-248768; fax 44-1865-791237; e-mail meetings@rms.org.uk; <http://www.rms.org.uk>.

12-14 Intl. Conf. on Aging Studies and Lifetime Extension of Materials, *Oxford, United Kingdom*. L.G. Mallinson, AWE Aldermaston, Reading RG7 4PR, U.K.; 44 (0)118 9827993; fax 44 (0)118 9824739; e-mail lmallinson@awe.co.uk.

12-14 SEMICON/West 99: Wafer Processing, *San Francisco, CA*. J. Sullivan, SEMI North America, 805 E. Middlefield Rd., Mountain View, CA 94043-4080; 650-964-5111; fax 650-967-5375; e-mail jsullivan@semi.org; <http://www.semi.org>.

12-16 Cryogenic Engineering Conf., and Intl. Cryogenic Materials Conf., *Montreal, Quebec, Canada*. Centennial Conferences, 303-499-2299; fax 303-499-2599; e-mail centennial@orci.com; <http://www.cec-icmc.org>.

14-16 7th Microoptics Conf., *Makuhari Messe, Chiba, Japan*. Y. Koike, Keio Univ., 3-14-1 Hiyoshi, Kohoku-ku, Yokohama 223-0061, Japan; 81-1-45-563-1141; fax 81-45-562-7373; e-mail y-koike@inst.keio.ac.jp; <http://www.din.or.jp/microopt/mocpof99.html>.

14-16 SEMICON/West 99; Test, Assembly and Packaging, *San Jose, CA*. J. Sullivan, SEMI North America, 805 E. Middlefield Rd., Mountain View, CA 94043-4080; 650-964-5111; fax 650-967-5375; e-mail jsullivan@semi.org; <http://www.semi.org>.

15-17 Conf. on Next Generation Packaging, *Solvang, CA*. Intl. Microelectronics and Packaging Society, 1850 Centennial Park Dr., Ste. 105, Reston, VA 20191-1517; 703-758-1060; fax 703-758-1066; e-mail imaps@imaps.org; www.imaps.org.

18-23 SPIE Annual Meeting and Optical Instrumentation Show, *Denver, CO*. SPIE, P.O. Box 10, Bellingham, WA 98227-0010; 360-676-3290; fax 360-647-1445; e-mail spie@spie.org; <http://www.spie.org>.

19-23 COLA'99: 5th Intl. Conf. on Laser Ablation, *Goettingen, Germany*. Dr. Michael Stuke, Max-Planck-Institut für Biophysikalische Chemie, PO Box 2841, D-37018 Goettingen, Germany; 49-551-201-1338 or 1314; fax 49-551-201-1330 or 1530; e-mail mstuke@gwdg.de.

19-23 OSA Topical Meetings on Integrated Photonics Research; Photonics in Switching; and Advanced Semiconductor Lasers and Their Applications, *Santa Barbara, CA*. Optical Society of America, Conf. Services Dept., 201 Massachusetts Ave., N.W., Washington, DC 20036-1023; 202-416-1980; fax 202-416-6100; e-mail confserv@osa.org; <http://www.osa.org/mtg-conf>.

19-23 Radiation Effects in Insulators, *Jena, Thuringia, Germany*. REI-10, c/o U. Bornkessel, Friedrich-Schiller-Univ. Jena, Inst. für Festkörperphysik, Max-Wien-Platz 1, D-07743 Jena, Germany; 49-3641-947315; fax 49-3641-947302; e-mail bornkessel@pinet.uni-jena.de; <http://www.physik.uni-jena.de/~exphys/rei10/>.

25-30 14th Intl. Conf. on the Chemistry of the Organic Solid State, *Cambridge, England*. ICCOSS XIV, W. Jones, Univ. of Cambridge, Dept. of Chemistry, Lensfield Rd., Cambridge CB1 2EW, United Kingdom; 44-1223-336468; fax 44-1223-336362; e-mail ICCOSSXIV@ch.cam.ac.uk.

25-30 26th Annual Review of Progress in Quantitative Nondestructive Evaluation, *Montreal, Quebec, Canada*. E-mail qnde3@conde.iastate.edu; www.conde.iastate.edu/qnde/qnde.html.

26-30 20th Intl. Conf. on Defects in Semiconductors, *Berkeley, CA*. ICDS-20, M/S 2-200, Berkeley Lab., Univ. of California, Berkeley, CA 94720; e-mail icds-20@lbl.gov; <http://www.lbl.gov/msd/ICDS-20>.

26-30 6th Intl. Conf. on the Structure of Surfaces, *Vancouver, Canada*. K.A.R. Mitchell, Dept. of Chemistry, Univ. of British Columbia, Vancouver, BC, Canada V6T 1Z1; 604-822-3266; fax 604-822-2847.

26-30 ICO Satellite Meeting on Light for Life, and Education and Training on Optics and Photonics Conf., *Cancun, Mexico*. SPIE, P.O. Box 10, Bellingham, WA 98227-0010; 360-676-3290; fax 360-647-1445; e-mail spie@spie.org; <http://www.spie.org>.

28-30 Education and Training on Optics and Photonics Conf., *Cancun, Mexico*. SPIE, P.O. Box 10, Bellingham, WA 98227-0010; 360-676-3290; fax 360-647-1445; e-mail spie@spie.org; <http://www.spie.org>.

AUGUST 1999

1-5 9th Intl. Conf. on Environmental Degradation of Materials in Nuclear Power Systems—Water Reactors, *Newport Beach, CA*. TMS Customer Service Dept., 420 Commonwealth Dr., Warrendale, PA 15086-7514; 724-776-9000; fax 724-776-3770; e-mail csc@tms.org; <http://www.tms.org/meetings/meetings.html>.

1-6 11th Conf. on Crystal Growth and Epitaxy, *Tucson, AZ*. T. Gentile, ACCGE-11 Secretariat, American Assoc. for Crystal Growth, P.O. Box 3233, Thousand Oaks, CA 91359-0233; 805-492-7047; fax 805-492-4062; e-mail aacg@lafn.org; <http://www.aml.arizona.edu/aacg>.

2-6 Denver X-ray Conf., *Steamboat Springs, CO*. D. Flaherty, Conf. Coordinator, ICDD, 12 Campus Blvd., Newtown Square, PA 19073-3273; 610-325-9814; fax 610-325-9823; e-mail flaherty@icdd.com; <http://www.dxcicdd.com>.

4-13 18th Intl. Union of Crystallography Congress, *Glasgow, Scotland, UK*. Northern Networking Ltd., Congress Central Office, Bellway House, 813 South Street, Glasgow G14 0BX, Scotland, UK; 44-141-954-4441; fax 44-141-954-2656; e-mail crystal@glasconf.demon.co.uk; <http://www.chem.gla.ac.uk/iucr99>.

9-13 12th Intl. Conf. on Textures of Materials, *Montreal, Quebec, Canada*. J.A. Szpunar, ICOTOM 12, Dept. of Metallurgical Engineering, McGill Univ., 3610 University St., Montreal, PQ, Canada, H3A 2B2.

15-20 2nd Conf. on Thermal Spray Processing of Nanoscale Materials, *Quebec City, Canada*. United Engineering Foundation, Three Park Ave., New York, NY 10016-5902; 212-591-7836; fax 212-591-7441; e-mail engfnd@aol.com; <http://www.engfund.org>.

22-26 Fall Natl. ACS Meeting, *New Orleans, LA*. Div. of Meetings, American Chemical Society, 1155 16th St. N.W., Washington, DC 20036; 202-872-4396; fax 202-872-6128; e-mail natlmtgs@acs.org; <http://www.acs.org>.

23-27 10th Intl. Conf. on Rapidly Quenched and Metastable Materials, *Bangalore, India*. S. Ranganathan and K. Chattopadhyay, Dept. of Metallurgy, Indian Inst. of Science, Bangalore 560012, India; 91-80-309-2678; fax 91-80-331-2991; e-mail rqtan@metalrg.iisc.ernet.in; <http://www.metalrg.iisc.ernet.in/~rqtan>.

23-27 18th Intl. Conf. on X-Ray and Inner-Shell Processes, *Chicago, IL*. X-99 Conf. Office, Physics Div., Argonne Natl. Lab., Bldg. 203, Rm. G-122, 9700 S. Cass Ave., Argonne, IL 60439-4843; 630-252-4044; fax 630-252-2864; e-mail x99@anl.gov; <http://www.phy.anl.gov/x99>.

27-29 1st Intl. Conf. on Scanning Probe Microscopy of Polymers, *Santa Barbara, CA*. T. Mehr, Conf. Coordinator, 112 Robin Hill Rd., Santa Barbara, CA 93117; 805-967-1401; e-mail terry@di.com; www.di.com/poly/poly.html.

30-3 11th Intl. Conf. on Thin Films, *Cancun, Mexico*. ICTF-11/SMCSVC-19, Dept. de Física, Centro de Investigación y de Estudios Avanzados del I.P.N.P.O., Box 14-740, Mexico 07000 D.F., Mexico; 52-5-7477000; fax 52-5-7477096; e-mail ictf99@fis.cinvestav.mx.

30-3 Conf. on Lasers and Electro-Optics/Pacific Rim, *Seoul, Korea*. Optical Society of Korea, Rm. 811, Korea Science & Technology Ctr., 635-4, Yucksamdong, Kangnam-ku, Seoul 135-703, Korea; 82-2-3452-6560; fax 82-2-3452-6561.

SEPTEMBER 1999

1-3 OSA Topical Meeting on Nonlinear Guided Waves and Their Applications, *Dijon, France*. Optical Society of America, Conf. Services Dept., 2010 Massachusetts Ave., N.W., Washington, DC 20036-1023; 202-416-1980; fax 202-416-6100; e-mail confserv@osa.org; <http://www.osa.org/mtg-conf>.

1-4 Surfaces in Biomaterials Conf., *Scottsdale, AZ*. Surfaces in Biomaterials Foundation, 13355 10th Ave. N., Minneapolis, MN 55441; 612-915-1011; fax 612-927-8127; <http://www.surfaces.org>.

2-8 6th Intl. Conf. on Hydrogen Materials Science and Chemistry of Metal Hydrides, *Katsiveli, Yalta, Ukraine*. D.V. Schur, S. Yu Zaginaichenko, Program Committee ICHMS'99, P.O. Box 195, Kiev-150, 252150, Ukraine; phone/fax 380-44-444-0001; e-mail shurzag@ipms.kiev.ua.

5-7 ICSSS—International Conference on Solid State Spectroscopy, *Schwäbisch Gmünd, Germany*. Sabine Birtel, fax 49-711-689-1712; e-mail icsss@cardix.mpi-stuttgart.mpg.de; <http://cardix.mpi-stuttgart.mpg.de/icsss/>.

5-9 15th European Conf. on Thermophysical Properties, *Würzburg, Germany*. J. Fricke, ZAE Bayern, Am Hubland, D-97074 Würzburg, Germany; e-mail ectp@zae.uni-wuerzburg.de; <http://www.zae-bayern.de/ectp>.

5-9 Extraction and Process Metallurgy Conf., and World Congress on Recycling Waste Treatment and Minimization of Wastes, *San Sebastian, Spain*. Customer Service Dept., TMS, 420 Commonwealth Dr., Warrendale, PA 15086; 724-776-9000; fax 724-776-3770; e-mail csc@tms.org; <http://www.tms.org>.

6-8 6th Intl. Conf. on Interfacial Phenomena in Composite Materials, *Berlin, Germany*. A. Hampe, BAM, Berlin, Germany; 49-30-8104-1600; fax 49-30-8104-1607; e-mail andreas.hampe@bam.de.

6-9 Euro-Fillers '99 Conf., *Lyon-Villeurbanne, France*. Euro-Fillers '99 Secretariat, Lab. des Matériaux, Macromoléculaires, Inst. Natl. des Sciences Appliquées, Bât. 403-20, Ave. Albert Einstein, 69621 Villeurbanne Cedex, France; 33-4-7243-8979; fax 33-4-7243-8527; e-mail eurofillers@insa-lyon.fr.

6-10 8th Intl. Conf. on Ion Sources, *Kyoto, Japan*. J. Ishikawa, Electronic Science and Engineering Dept., Kyoto Univ., Yoshida-homomachi, Sakyo-ku, Kyoto 606-8501, Japan; 81-75-753-5325; fax 81-75-753-5324; e-mail icis99@mvtpc3.kuee.kyoto-u.ac.jp; <http://mvtpc3.kuee.kyoto-u.ac.jp/icis99>.

10-15 10th Intl. Conf. on Recent Progress in Many-Body Theories, *Seattle, WA*. A. Bulgac, Dept. of Physics, Univ. of Washington, P.O. Box 351560, Seattle, WA 98195-1560; fax 206-685-9829; e-mail mbx@phy.washington.edu; <http://www.phys.washington.edu/~mbx>.

12-16 4th Intl. Conf. on Nuclear Physics at Storage Rings, *Bloomington, IN*. J. Meadows, Indiana Univ. Cyclotron Facility, 2401 Milo B. Sampson Lane, Bloomington, IN 47408; 812-855-9365; 812-855-6645; e-mail stori99@iucf.indiana.edu.

13-15 4th Intl. Conf. on Spray Forming, *Baltimore, MD*. J. Abrahams, Conf. Secretariat, "Beggars Roost," Channels End Rd., Colmworth, Bedfordshire MK44 2NS, UK; 44-12-34-37-8862; fax 44-12-34-37-6219; e-mail 100700.2023@compuserve.com.

13-17 7th Intl. Conf. on Microwave and High Frequency Heating, *Valencia, Spain*. 7th Intl. Conf. Microwave & HF Heating, TOT NOU, C/Ciriolo Amorós, 27-2°-C, E-46004 Valencia, Spain; 34-96-394-3445; fax 34-96-394-1654; e-mail microwav@etsit.upv.es; <http://www.digital.es/icom/totnou>.

19-23 Specialty Conf. on Copper, *Phoenix, AZ*. Customer Service Dept., TMS, 420 Commonwealth Dr., Warrendale, PA 15086; 724-776-9000; fax 724-776-3770; e-mail csc@tms.org; <http://www.tms.org>.

20-24 ▼ 3rd Conf. of the Yugoslav Materials Research Society, *Herceg Novi, Yugoslavia*. Yu-MRS Conf. Secretariat, Inst. of Technical Sciences of the Serbian Academy of Sciences and Arts, Knez Mihailova 35/IV, P.O. Box 745, 11000 Belgrade, Yugoslavia; 381-11-185-437; fax 381-11-185-263; e-mail yumrs@itn.sanu.ac.yu; <http://www.yu-mrs.org.yu>.

21-23 1st Intl. SAMPE Automotive Conf., Meeting of the Engineering Society, and the Engineering Society/Society of Automotive Engineers Intl. Body Engineering Conf., *Detroit, MI*. C.L. Hammermesh, Technical Director, Society for Advancement of Material and Process Engineering, SAMPE Intl. Business Office, P.O. Box 2459, Covina, CA 91722-8459; 626-331-0616; fax 626-332-8929.

21-24 ▼ 18th European Conf. on Surface Science, *Vienna, Austria*. ECOSS-18 Secretary, Inst. für Allgemeine Physik, TU-Wien, Wiedner Hauptstr. 8-10/E134, A-1040 Vienna, Austria.

24-26 ▼ OSA/ACS Topical Meeting on Organic Thin Films for Photonics Applications; with OSA Topical Meeting on Bragg Coatings, Photosensitivity, and Poling in Glass Waveguides; *Santa Clara, CA*. Optical Society of America, Conf. Services Dept., 2010 Massachusetts Ave., N.W., Washington, DC 20036-1023; 202-416-1980; fax 202-416-6100; e-mail confserv@osa.org; <http://www.osa.org/mtg-conf>.

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Process modeling

Film properties

Microstructure, grain size, texture
Electrical properties
Mechanical properties (stress, relaxation, etc.)

New interconnect and dielectric materials

Low-R metals (Cu, Cu alloys, Ag, Au)
Low-k dielectrics (spin-on/vapor deposited polymers, porous materials, etc.)
Diffusion barriers (Ta-, Ti-, W-based, ternary, amorphous, etc.)
High-k dielectrics (BST, PZT, tantalum pentoxide, etc.)

Electrodes for high-k capacitors (Ru, Pt, Ir, etc.)
Novel materials for ferroelectric memories

Novel interconnects (high frequency, optical, superconductors, etc.)

Deposition and planarization methods

CVD of metals and dielectrics
Advanced PVD of metals and dielectrics
Electrochemical and electroless deposition
Chemical mechanical polishing (metals, SiO₂-based and low-k dielectrics)
CMP endpoint detection/metrology
Alternative planarization techniques

Process integration issues

Silicides, salicides
Advanced gate metallization
High-k capacitor technology
PMD/ILD multilayer deposition/planarization
Advanced pattern/etch techniques for metals and dielectric materials
Barrier/liner/fill technology for holes and damascene architecture
Advanced Al technology
Integration of copper and low-k dielectrics and other new materials

Reliability and performance

(including modeling and simulation)
Electromigration, stress migration
Low-k dielectrics
Interconnect and device characteristics (signal delay, crosstalk, etc.)

Bonding and packaging technology

Bonding and packaging for new interconnect materials
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Environmental health and safety issues

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26-1 OSA Annual Meeting, and Interdisciplinary Laser Science Conf., *Santa Clara, CA*. Optical Society of America, Conf. Services Dept., 2010 Massachusetts Ave., N.W., Washington, DC 20036-1023; 202-416-1980; fax 202-416-6100; e-mail confserv@osa.org; http://www.osa.org/mtg-conf.

27-29 1st Intl. SAMPE Automotive Conf., with ESD Advanced Coatings Technology Conf., *Detroit, MI*. Society for the Advancement of Material and Process Engineering, 1161 Parkview Dr., Covina, CA 91724-3748; 626-331-0616; fax 626-332-8929; e-mail sampeibo@aol.com; www.byu.edu/~sampe.

27-30 European Conf. on Advanced Materials and Processes, *Munich, Germany*. EUROMAT Congress Office, c/o Deutsche Gesellschaft für Materialkunde, Hamburger Allee 26, D-60486 Frankfurt, Germany; 49-69-7917-750; fax 49-69-7917-733; http://www.fems.org.

OCTOBER 1999

4-7 IEEE Intl. Silicon-on-Insulator Conf., *Rohnert Park, CA*. BACM, 520 Washington Blvd., Ste. 350, Marina del Rey, CA 90292; 310-305-7885; fax 310-305-1038; e-mail bacm@mediaone.net; http://www.drcsdca.com/%7esoicnf-www.drcsdca.com/~soicnf.

4-8 8th European Conf. on Applications of Surface and Interface Analysis, *Sevilla, Spain*. ECASIA99, Dept. Física Aplicada, C-XII, Facultad de Ciencias, Univ. Autónoma de Madrid, Cantoblanco E 28049, Madrid, Spain; fax 34-1-397-3969; e-mail josem.sanz@uam.es; http://www.uam.es/fai/ecasia99.html.

10-15 9th Intl. Conf. on Fusion Reactor Materials, *Colorado Springs, CO*. R.H. Jones, ICFRM-9 General Chairperson, Pacific Northwest National Lab., P.O. Box 999, MSIN P8-15, Richland, WA 99352; 509-376-3701; fax 509-376-0418; e-mail bev.wardlow@pnl.gov.

17-22 196th Meeting of The Electrochemical Society and Fall Meeting of The Electrochemical Society of Japan, *Honolulu, HI*. The Electrochemical Society, 10 S. Main St., Pennington, NJ 08534-2896; 609-737-1902; fax 609-737-2743; e-mail ecs@electrochem.org; http://www.electrochem.org.

19-20 SEMICON/Southwest, *Austin, TX*. J. Sullivan, SEMI North America, 805 E. Middlefield Rd., Mountain View, CA 94043-4080; 650-964-5111; fax 650-967-5375; e-mail jsullivan@semi.org; http://www.semi.org.

25-29 AVS 46th Intl. Symposium, *Boston, MA*. American Vacuum Society, 120 Wall St., 32nd Floor, New York, NY 10005-3993; 212-248-0200; fax 212-248-0245; e-mail avsnyc@vacuum.org; http://www.vacuum.org.

26-28 32nd Intl. Symposium on Microelectronics, *Chicago, IL*. Intl. Microelectronics and Packaging Society, 1850 Centennial Park Dr., Ste. 105, Reston, VA 20191-1517; 703-758-1060; fax 703-758-1066; e-mail imaps@imaps.org; www.imaps.org.

26-30 31st Intl. SAMPE Technical Conf., with the Composite Fabricators Association, *Chicago, IL*. Society for the Advancement of Material and Process Engineering, 1161 Parkview Dr., Covina, CA 91724-3748; 626-331-0616; fax 626-332-8929; e-mail sampeibo@aol.com; www.et.byu.edu/~sampe.

NOVEMBER 1999

1-3 3rd North American Conf. on the Science and Technology of Emulsion Polymers/Polymer Colloids, *Hilton Head Island, SC*. Inst. of Materials Science, 75 S. Manheim Blvd., New Paltz, NY 12561; 914-255-0757; fax 914-255-0978; e-mail nainquiry@ims-np.org/narcCol.

1-3 Intl. Conf. on the Science, Technology, and Applications of Sintering, *State College, PA*. R. Cornwall, Materials Research Lab., 277 MRL, Pennsylvania State Univ., University Park, PA 16802; 814-863-8735; fax 814-863-9704; e-mail rgc5@psu.edu; http://www.pmlab.psu.edu/sint99.

1-4 ASM Intl. Materials Solutions Conf., *Cincinnati, OH*. ASM Intl., Materials Park, OH 44703-0002; 440-338-5151; fax 440-338-4634; www.asm-intl.org.

8-10 3rd ISOPE Ocean Mining Symposium, *Goa, India*. Intl. Society of Offshore and Polar Engineers, P.O. Box 1107, Golden, CO 80402-1107; 303-420-8114; fax 303-420-3760.

15-18 2nd Intl. Conf. on Processing Materials for Properties, *San Francisco, CA*. Customer Service Dept., TMS, 420 Commonwealth Dr., Warrendale, PA 15086; 724-776-9000; fax 724-776-3770; e-mail csc@tms.org; http://www.tms.org.

29-3 MRS Fall Meeting, *Boston, MA*. Materials Research Society, 506 Keystone Drive, Warrendale, PA 15086-7573; 724-779-3003; fax 724-779-8313; http://www.mrs.org/ MRS.

DECEMBER 1999

1-3 SEMICON Japan 99, *Chiba, Japan*. J. Sullivan, SEMI North America, 805 E. Middlefield Rd., Mountain View, CA 94043-4080; 650-964-5111; fax 650-967-5375; e-mail jsullivan@semi.org; http://www.semi.org.

JANUARY 2000

2-7 2nd World Congress on Microwave Processing, *Orlando, FL*. D.E. Clark, Organizing Committee Chair, Dept. of Materials Science and Engineering, 136 MAE, Univ. of Florida, P.O. Box 116400, Gainesville, FL 3211-6400. Endorsed.

FEBRUARY 2000

7-9 2000 IEEE Intl. Solid-State Circuits Conf., *San Francisco, CA*. D. Suiters; 202-331-2000; e-mail isscc@courtesyassoc.com.

20-24 TMS Annual Meeting, *Nashville, TN*. Customer Service Dept., TMS, 420 Commonwealth Dr., Warrendale, PA 15086; 724-776-9000; fax 724-776-3770; e-mail csc@tms.org; http://www.tms.org.

MARCH 2000

5-10 Optical Fiber Communication Conf., *Baltimore, MD*. Optical Society of America, Conf. Services Dept., 2010 Massachusetts Ave., N.W., Washington, DC 20036-1023; 202-416-1980; fax 202-416-6100; e-mail confserv@osa.org; http://www.osa.org/mtg-conf.

6-8 Polymer Stabilizers and Modifiers Conf., *Hilton Head Island, SC*. Inst. of Materials Science, 75 S. Manheim Blvd., New Paltz, NY 12561; 914-255-0757; fax 914-255-0978; e-mail nainquiry@ims-np.org/narcStab.

20-24 APS 2000 March Meeting, *Minneapolis, MN*. Meetings Dept., American Physical Society, One Physics Ellipse, College Park, MD 20740-3844; 301-209-3286; http://www.aps.org.

APRIL 2000

3-4 Microscopy of Composite Materials V, *Oxford, UK*. Royal Microscopical Society, 37/38 St. Clements, Oxford OX4 1AJ, UK; 44-1865-248768; fax 44-1865-791237; e-mail meetings@rms.org.uk; http://www.rms.org.uk.

11-13 Intl. Microscopy Conf., *London, UK*. Royal Microscopical Society, 37/38 St. Clements, Oxford OX4 1AJ, UK; 44-1865-248768; fax 44-1865-791237; e-mail meetings@rms.org.uk; http://www.rms.org.uk.

16-19 6th Intl. Multi-disciplinary Conf.: Complexity and Fractals in the Sciences, *Singapore*. http://www.kingston.ac.uk/fractal.

24-28 MRS Spring Meeting, *San Francisco, CA*. Materials Research Society, 506 Keystone Drive, Warrendale, PA 15086-7573; 724-779-3003; fax 724-779-8313; http://www.mrs.org/ MRS.

MAY 2000

7-12 Conf. on Lasers and Electro-Optics, and Quantum Electronics and Laser Science Conf., *San Francisco, CA*. Optical Society of America, Conf. Services Dept., 2010 Massachusetts Ave., N.W., Washington, DC 20036-1023; 202-416-1980; fax 202-416-6100; e-mail confserv@osa.org; http://www.osa.org/mtg-conf.

15-20 6th World Biomaterials Congress, *Kamuela (Big Island), HI*. Society for Biomaterials, 13355 10th Ave. N., Ste. 108, Minneapolis, MN 55441; 612-927-8108; fax 612-927-8127; e-mail biomaterials.org; http://www.biomaterials.org.

22-27 26th Congress on Chemical Engineering, Environmental Protection, and Biotechnology, *Frankfurt am Main, Germany*. DECHEMA Deutsche Gesellschaft für Chemisches Apparatewesen, Chemische Technik und Biotechnologie e.V., Th. Scheuring, Germany; 49-69-7564-230; fax 49-69-7564-298; http://www.dechema.de.

28-2 10th Intl. Offshore and Polar Engineering Conf., *Seattle, WA*. Intl. Society of Offshore and Polar Engineers, P.O. Box 1107, Golden, CO 80402-1107; 303-420-8114; fax 303-420-3760.

JULY 2000

17-21 5th Intl. Conf. on Diffusion in Materials, *Paris, France*. DIMAT 2000, DEC/M SRMP, Bat. 520, CEA/SACLAY, 91191 Gif-sur-Yvette Cedex, France; e-mail dimat2000@cea.fr; www.dimat2000.cea.fr.

30-4 SPIE Annual Meeting, *San Diego, CA*. SPIE, P.O. Box 10, Bellingham, WA 98227-0010; 360-676-3290; fax 360-647-1445; e-mail spie@spie.org; http://www.spie.org.

SEPTEMBER 2000

3-8 Congress of Histochemistry and Cytochemistry, *York, UK*. Royal Microscopical Society, 37/38 St. Clements, Oxford OX4 1AJ, UK; 44-1865-248768; fax 44-1865-791237; e-mail meetings@rms.org.uk; http://www.rms.org.uk.

10-15 Conf. on Lasers and Electro-Optics/Europe, and Intl. Quantum Electronics Conf., *Nice, France*. Optical Society of America, Conf. Services Dept., 2010 Massachusetts Ave., N.W., Washington, DC 20036-1023; 202-416-1980; fax 202-416-6100; e-mail confserv@osa.org; http://www.osa.org/mtg-conf.

17-22 13th Intl. Conf. on Ion Implantation Technology, *Tyrol, Austria*. IIT 2000, c/o IIS-B, Schottkystrasse 10, 91058 Erlangen, Germany; 49-9131-761-100; fax 49-9131-761-102; e-mail iit2000@iis-b.fhg.de; http://www.mfa.kfki.hu/IIT2000.

OCTOBER 2000

2-6 AVS 47th Intl. Symposium, *Boston, MA*. American Vacuum Society, 120 Wall St., 32nd Floor, New York, NY 10005-3993; 212-248-0200; fax 212-248-0245; e-mail avsnyc@vacuum.org; http://www.vacuum.org.

20-28 OSA Annual Meeting, *Providence, RI*. Optical Society of America, Conf. Services Dept., 2010 Massachusetts Ave., N.W., Washington, DC 20036-1023; 202-416-1980; fax 202-416-6100; e-mail confserv@osa.org; http://www.osa.org/mtg-conf.

NOVEMBER 2000

13-14 ASTM Symposium on Marine Corrosion in Tropical Environments, *Merida, Yucatan, Mexico*. V. Chaker, Port Authority of NY-NJ, One World Trade Ctr., 74W, New York, NY 10048; 212-435-5790; fax 215-435-8040.

27-1 MRS Fall Meeting, *Boston, MA*. Materials Research Society, 506 Keystone Drive, Warrendale, PA 15086-7573; 724-779-3003; fax 724-779-8313; http://www.mrs.org/ MRS. □

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